

Appl. No. : 10/022,297
Filed : December 12, 2001

IN THE SPECIFICATION:

Attached hereto is a marked-up version of the changes made to the specification by the current amendment. The attached pages are captioned *VERSION OF SPECIFICATION WITH MARKINGS TO SHOW MODIFICATIONS UNDER 37 C.F.R. §§ 1.121(b)(iii)*.

On pages 7-8, replace paragraph [0047] with the following paragraph:

B1
[0047] As shown in FIGURES 9 and 10, the terminal bar 62A, for example, preferably comprises copper plate and is shaped generally as an S-configuration. The terminal bar 62A comprises a bottom horizontal section 96A, a vertical section 98A and a top horizontal section 100A. The bottom section 96A preferably defines two apertures 102A. The printed wiring board 72 also defines two apertures 103A (FIGURE 4) corresponding to the apertures 102A of the bar 62A. The rivets 94 pass through the apertures to couple the bottom section 96A with the printed wiring board 72. The vertical section 98A defines an aperture 104A. The top section 100A defines an aperture 105A. The terminal bar 62B preferably comprises the same material, is shaped in substantially the same configuration, and has similar apertures. Since the terminal bar 62B is similar to the terminal bar 62A except for its size and except for the positions of the apertures, the same reference numerals are assigned to corresponding portions of the terminal bar 62B but with the letter B. Because the sizes of the respective terminal bars 62A, 62B and the positions of the apertures 104A, 105A, 105B are shown in FIGURES 6-10, further descriptions about the sizes and the positions are not deemed necessary. Note that the bottom apertures (not shown) of the terminal bar 62B are positioned to match the apertures 103B in FIGURE 4.

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On page 8, replace paragraph [0048] with the following paragraph:

B2
[0048] The capacitor 64 has a pair of terminals 106A, 106B that are disposed on the same side and are formed with threaded holes. Two bolts 108A, 108B are fitted into the apertures 104A, 104B of the respective terminal bars 62A, 62B and are further fitted into the threaded holes of the terminals 106A, 106B. Thus, the vertical sections 98A, 98B of the terminal bars 62A, 62B together support the capacitor 64. A pair of power cables can be connected with the respective apertures 105A, 105B to couple the terminal bars 62A, 62B with the battery 58.

On page 8, replace paragraph [0049] with the following paragraph:


B3
[0049] Another terminal bar 62C, which is similar to the terminal bars 62A, 62B, is affixed to the printed wiring board 72 below the circuit board 88. Although the terminal bar 62C only has a nominal vertical section and no aperture is provided in the vertical section, the same reference numerals are assigned to the corresponding portions but with the letter C. Note that the bottom apertures (not shown) of the terminal bar 62C are positioned to match the apertures 103C in FIGURE 4. The terminal bar 62C is connected with the drains D of the FETs 66. A power cable can be connected with the aperture 105C to couple the terminal bar 62C with the motor 54.

On pages 14-15, replace paragraph [0071] with the following paragraph:

B4
[0071] FIGURES 22-26 illustrate a further method using the reflow furnace and a mounting tool. As shown in FIGURE 22, at a step S31, the part moulder mounts parts 160 onto each predetermined location on the substrate 72 as shown in FIGURES 23-25. The cream solder 146 is previously applied at the respective portions of the parts which are soldered. At a next step S32, a mounting tool 162 is set for positioning the semiconductor chips 66 at predetermined locations. The

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 tool 162 has windows 164 through which the semiconductor chips 66 can be mounted. The chip mounter, at a step S33, mounts the semiconductor chips 66 onto the cream solder 146 applied on the lands 144 through the windows 164. Weights 166 are placed on the respective semiconductor chips 66. At a step S34, the substrate 72 with the semiconductor chips 66 and the parts 160 are put in the reflow furnace to fix to the substrate 72 by the hot blast. In this step S34, the tool 162 advantageously prevents the semiconductor chips 66 from slipping off the preset positions. The weights also are useful to prevent voids from being generated in the solder 146 or to expedite the bubbles to escape from the solder 146 in the step S34. At a last step S35, the tool 162 and the weights 166 are detached.
